



SOT1161-2

XQFN16, plastic, extremely thin quad flat package; no leads;
16 terminals; 2.6 mm x 1.8 mm x 0.50 mm body

26 January 2021

Package information

1 Package summary

Terminal position code	Q (quad)
Package type descriptive code	XQFN16
Package type industry code	XQFN16
Package style descriptive code	XQFN (extremely thin quad flatpack; no leads)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	24-01-2017
Manufacturer package code	SOT1161

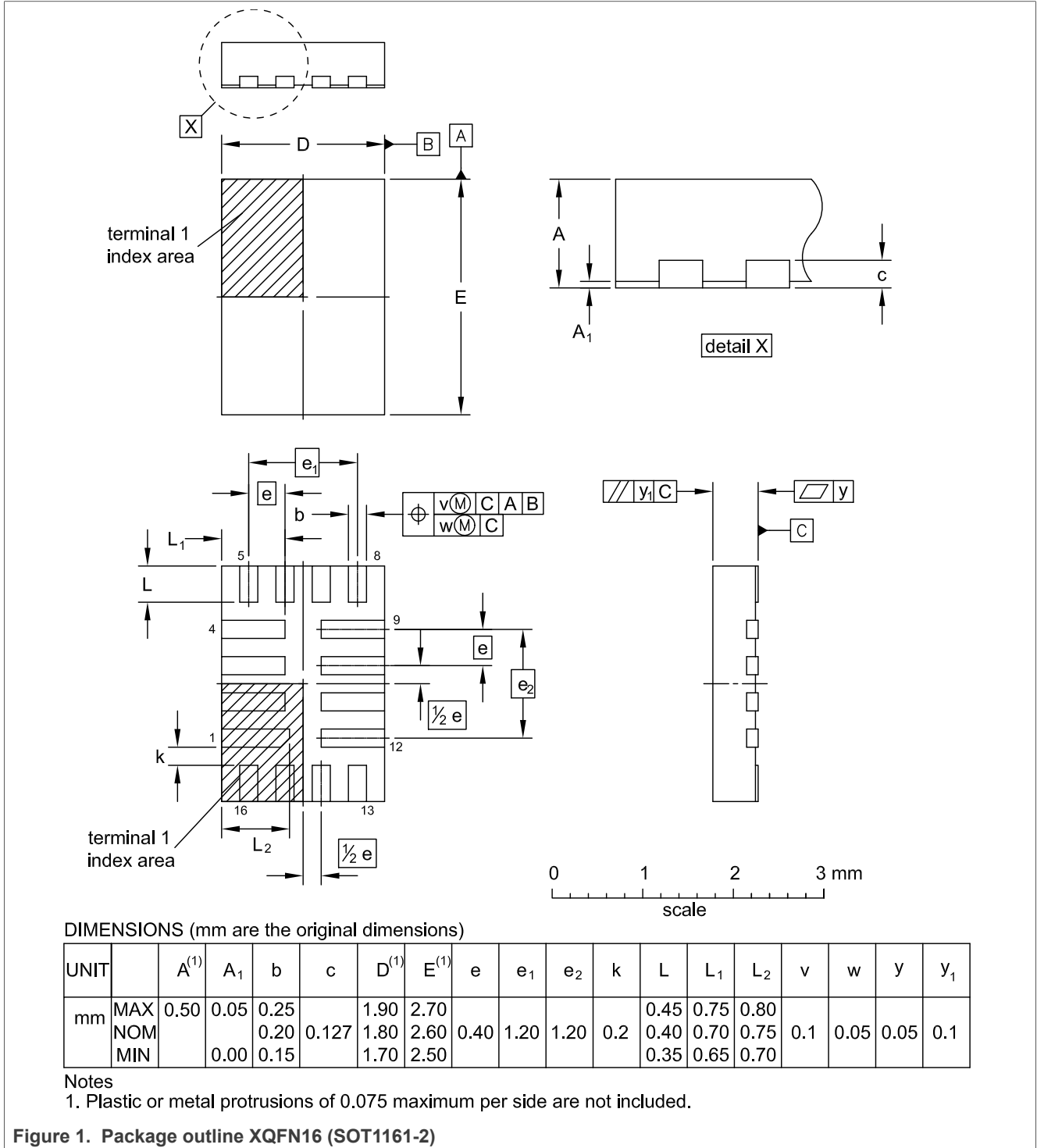
Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	1.7	1.8	1.9	mm
package width	2.5	2.6	2.7	mm
seated height	-	-	0.5	mm
nominal pitch	-	0.4	-	mm
actual quantity of termination	-	16	-	



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2 Package outline



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3 Soldering

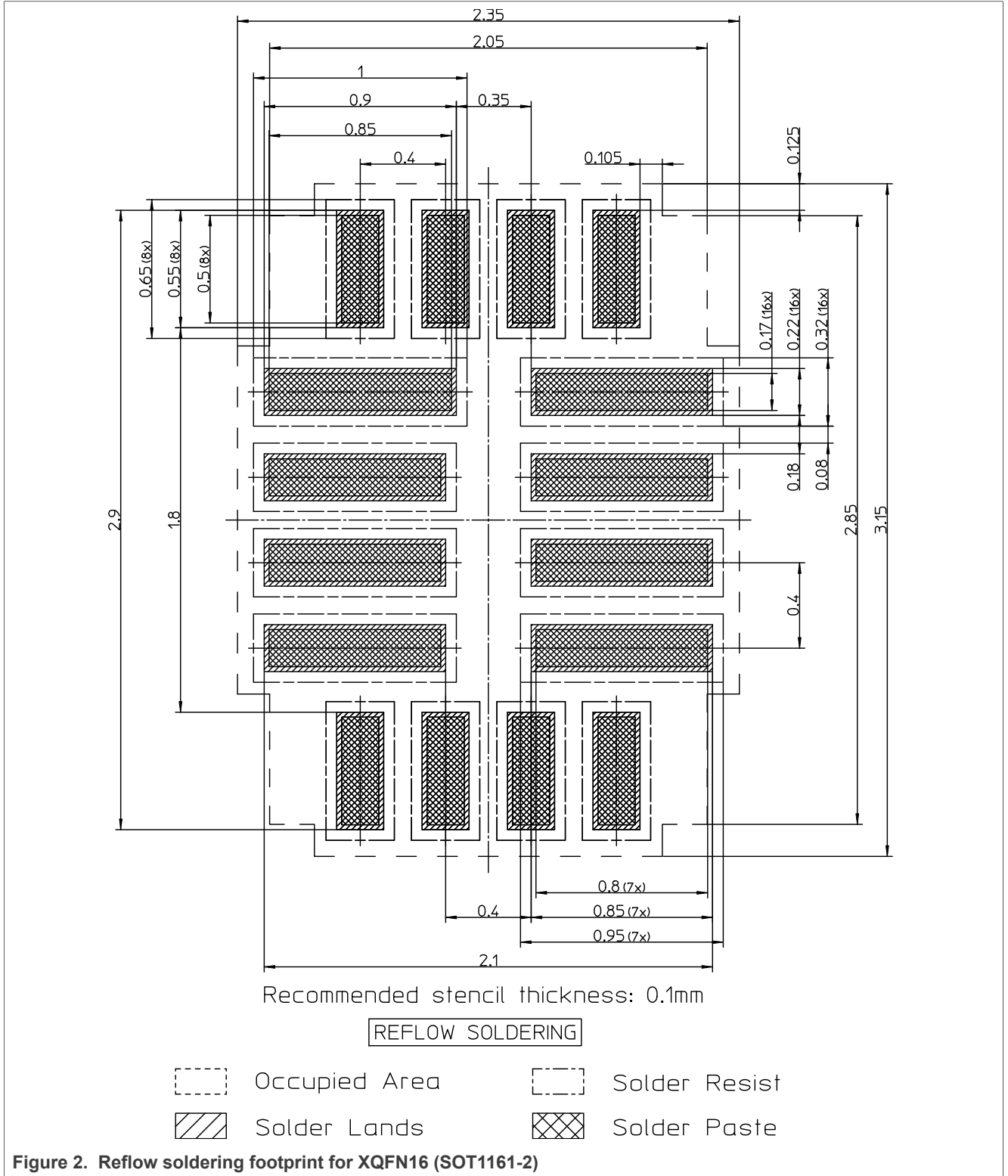


Figure 2. Reflow soldering footprint for XQFN16 (SOT1161-2)

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4 Legal information

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